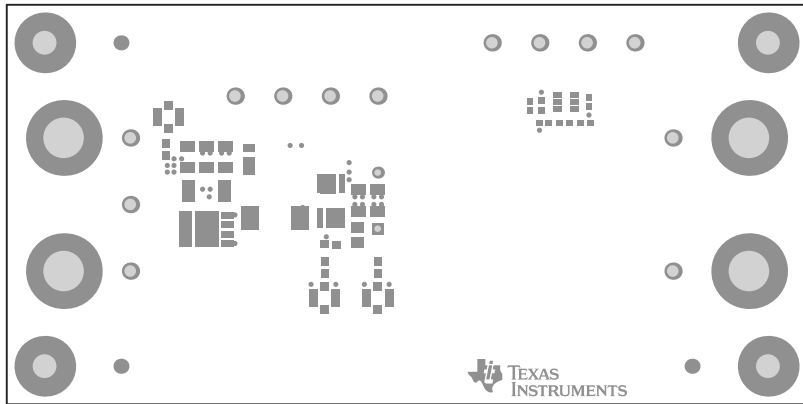
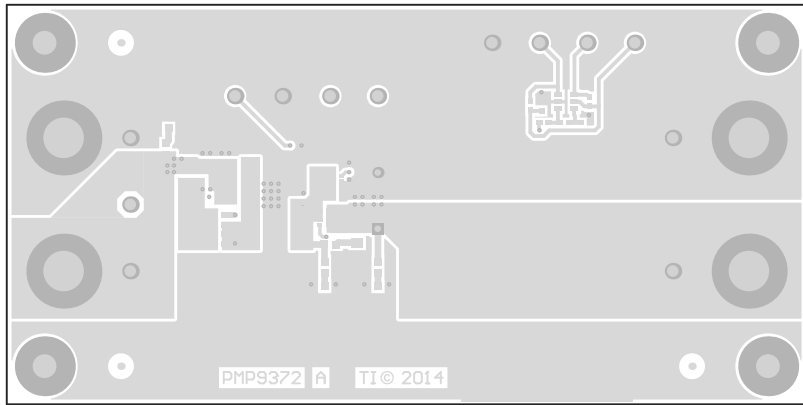


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/14/2014 12:49:30 PM	TEXAS INSTRUMENTS	



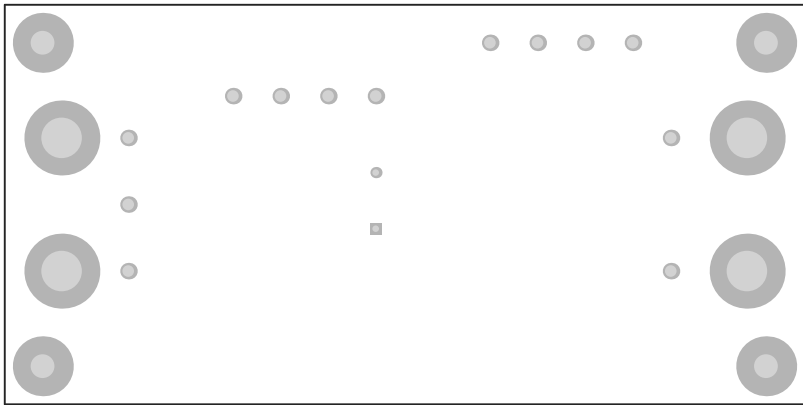
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/14/2014 12:49:31 PM	TEXAS INSTRUMENTS	



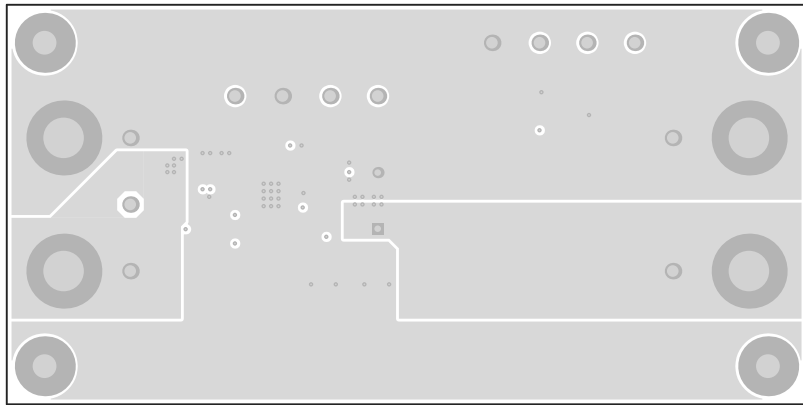
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/14/2014 12:49:31 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = InternalPlane1			
PLOT NAME = InternalPlane1	GENERATED : 3/14/2014 12:49:32 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 3/14/2014 12:49:32 PM	TEXAS INSTRUMENTS	

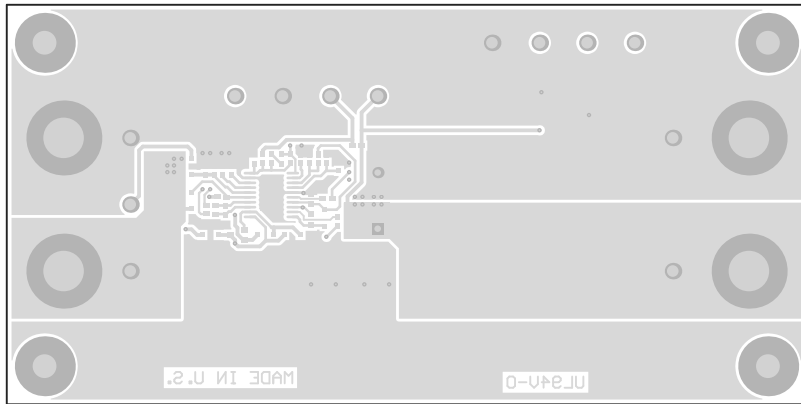


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = MidLayer2	GENERATED : 3/14/2014 12:49:33 PM	TEXAS INSTRUMENTS	

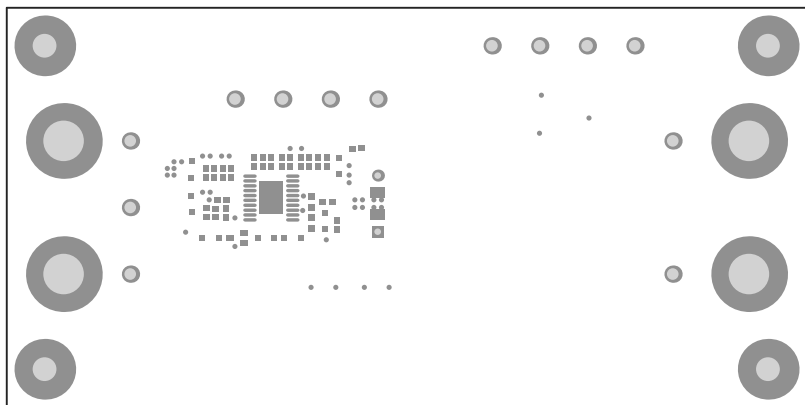


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = InternalPlane2			
PLOT NAME = InternalPlane2	GENERATED : 3/14/2014 12:49:33 PM	TEXAS INSTRUMENTS	

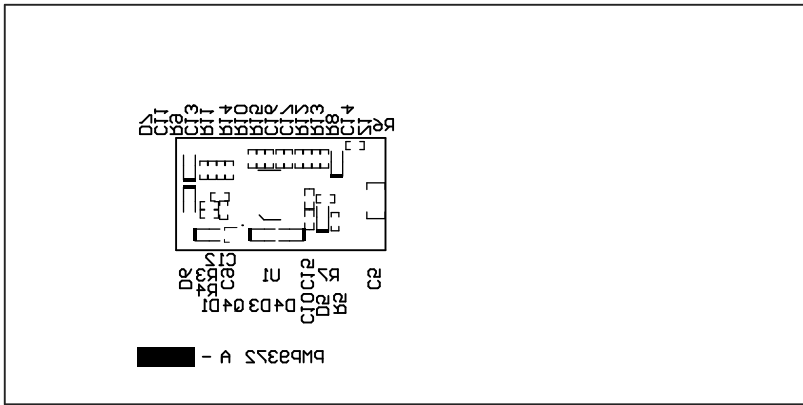
SUN: Not In VersionControl



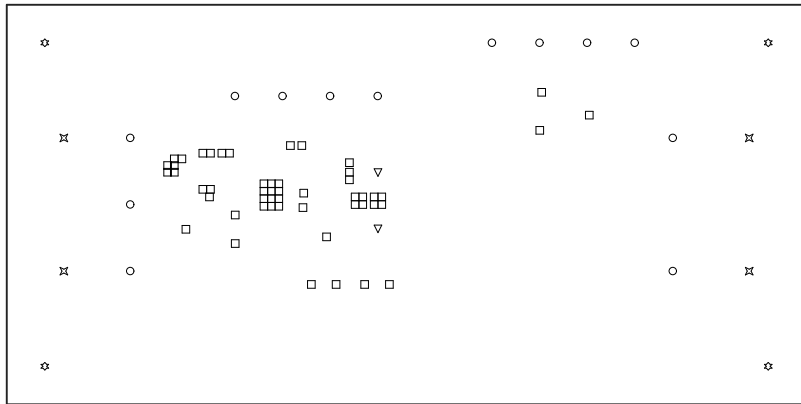
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/14/2014 12:49:33 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/14/2014 12:49:34 PM	TEXAS INSTRUMENTS	



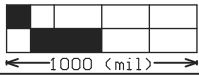
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/14/2014 12:49:34 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	51	10mil (0.254mm)	PTH	Round
▽	2	35.433mil (0.9mm)	PTH	Round
○	13	63mil (1.6mm)	PTH	Round
✱	4	125.984mil (3.2mm)	PTH	Round
⌘	4	214.567mil (5.45mm)	PTH	Round
	74 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/14/2014 12:49:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9372	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/14/2014 12:49:35 PM	TEXAS INSTRUMENTS	

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